Content of Press Kit

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REN2604 **Renesas Expands Auto MCU Portfolio with 28nm RH850/U2C for Vehicle Control and Automotive Safety Applications**	
REN2603 **Renesas R-Car V4H ADAS SoC Selected for Toyota RAV4 Model**	
REN2602 **Renesas Develops SoC Technologies for Automotive Multi-Domain ECUs Essential for the SDV Era**	

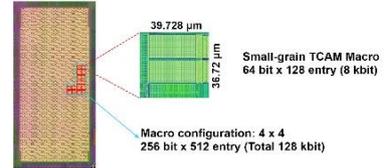| News releases in English, German, French & Italian	Images
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REN2531 **Renesas Fast-Tracks SDV Innovation with R-Car Gen 5 SoC-Based End-to-End Multi-Domain Solution Platform**	
REN2530 **Renesas Releases its First Wi-Fi 6 and Wi-Fi/Bluetooth LE Combo MCUs for IoT and Connected Home Applications**	
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REN2528 **Renesas Adds Two New MCU Groups to Blazing Fast RA8 Series with 1GHz Performance and Embedded MRAM**	
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